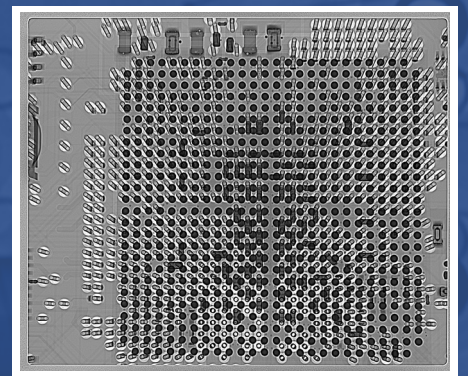
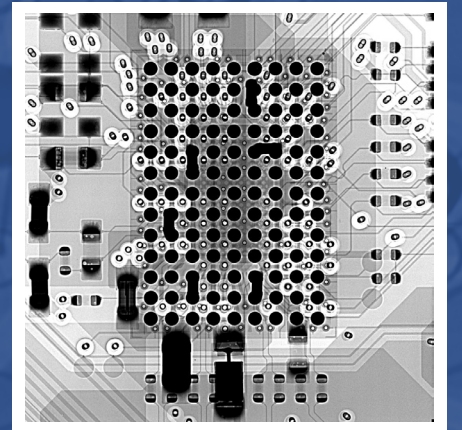
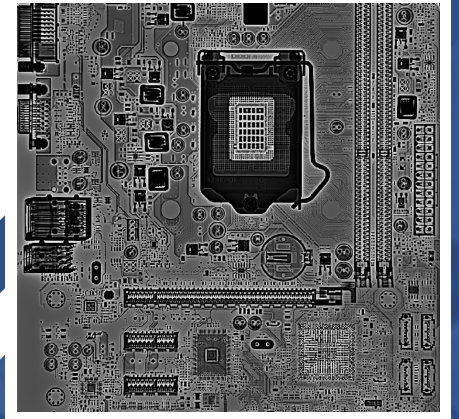


PCB X-RAY INSPECTION SOLUTIONS



- For BGA and Void analysis
- High-Precision Inspection for Enhanced Quality
- Inspection for Enhanced Efficiency and Reliability

TECHNICAL SPECIFICATIONS

Model	Small			Large		
X-Ray tube	160KV	160 KV	190 KV	160KV	160 KV	190 KV
Type	Open					
Focal spot (micron)	0.25			0.25		
JIMA resolution (micron)		0.9			0.9	
Target power (W)	8 W (Beryllium window) / 16 W (Diamond window [sold separately])	10		8 W (Beryllium window) / 16 W (Diamond window [sold separately])	10	
X-Ray beam angle	140	160		140	160	
Min SOD (mm)	0.5	0.25		0.5	0.25	
Sample size (mm)	440 X 550			800 X 500		
Max sample weight	5 Kg			7 Kg		
Max Radioscopic area (mm)	310 X 310			460 X 410		
Detector tilt	± 60 DEG	± 70 DEG		± 60 DEG	± 70 DEG	
Detector	1313	1308	1515	1313	1308	1515
Pixel pitch (micron)	127			127		
System dimensions (W/D/H)	1000X1050X2200			1650X1400X2050		
System weight (kg)	1450			2200		
PCB tray for 2D	Rectangular					
PCB tray for 2D & 2.5D (option)	Circular					
PCB holder for 3D CT (option)	PCB holder					
CT modes	Laminography/Quick scan/Quality scan					
BGA inspection	BGA detection/BGA count/BGA void identification/BGA voids					
THT inspection	fill percentage in THT / accept / Reject					
Optical camera image overview	Available					

KEY FEATURES

- Quality of Soldering joints in SMD / SMT and profiling of SMD / SMT
- Up to 8µm High - Resolution images with MIS Software
- Designed as per AERB safety guidelines (AERB / RF-IR / SC-1)
- PLC-based manipulator control system with Nano/micro focus X-Ray tube of maximum standard energy range 190kV